

LISTING OF THE CLAIMS

This listing of claims replaces all prior versions and listings of claims in the application:

1. - 2. (Canceled)

3. (Currently Amended) A substrate processing apparatus for processing a substrate with a plurality of processing solutions having different components, said apparatus comprising:

a holding element provided on a rotating base, for holding a peripheral portion of a substrate to keep said substrate in a substantially-horizontal position;

a rotation element for rotating said substrate held by said holding element about an axis along a substantially-vertical direction;

an atmosphere cutoff plate positioned above said holding element, facing a top surface of said substrate held by said holding element; and

a first up-and-down moving element for moving said atmosphere cutoff plate up-and-down;

a splash prevention element for receiving said plurality of processing solutions splashed from said peripheral portion of said substrate, comprising:

~~wherein said splash prevention element comprises:~~

a plurality of recovery ducts used for collecting said plurality of processing solutions, each duct of the plurality of recovery ducts comprising an upper guide member and a lower guide member; and

~~a selection element for selecting one duct of said plurality of recovery ducts for collecting a processing solution of the plurality of processing solutions used in a processing for said substrate;~~

a second up-and-down element for moving said plurality of recovery ducts up-and-down;
and

a control unit, configured to control the first up-and-down element moving the atmosphere cutoff plate up-and-down and the second up-and-down element moving a plurality of recovery ducts up-and-down when recovering one of the plurality of processing solutions at a chosen recovery duct from the plurality of recovery ducts, and to provide:

(i) a vertical spacing of an opening formed between said upper guide member and said lower guide member of a chosen recovery duct, greater than a spacing between said rotating base and said atmosphere cutoff plate;

(ii) a level position of a lower surface of said lower guide member of said chosen recovery ducts, not lower than a level of a lower surface of said rotating base near said opening; and

(iii) a level position of a top surface of the upper guide member of said chosen recovery ducts, not higher than a level of a top surface of said atmosphere cutoff plate near said opening,

wherein with a vertical thickness of said atmosphere cutoff plate [[is]] being greater than a vertical thickness of the upper guide member used for forming of said chosen recovery duct selected by said selection element, and a vertical thickness of said rotating base [[is]] being greater than a vertical thickness of the lower guide member used for forming of said chosen recovery duct selected by said selection element;

— a vertical spacing of each opening of said selected recovery duct formed by the upper guide member and the lower guide member used for forming said selected recovery duct is wider than a distance between said rotating base and said atmosphere cutoff plate; and

— a level of lower surface of the lower guide member is set not lower than a level of a lower surface of said rotating base near said opening, and a level of a top surface of the upper guide member is set not higher than a level of a top surface of said atmosphere cutoff plate near said opening, while the recovery duct is selected by said selection element, the level of the upper guide member and the level of the lower guide member used for forming said selected recovery duct are controlled and said processing solution are collected by said selected recovery duct.

4. **(Previously Presented)** The substrate processing apparatus according to claim 3, wherein said selected recovery duct has a shape curving downward, going away from a substrate with a vertical spacing almost equal to a vertical spacing of an opening thereof.

5. **(Previously Presented)** The substrate processing apparatus according to claim 3, wherein said selected recovery duct guides one of said plurality of processing solutions downward almost around a substrate.

6. **(Previously Presented)** The substrate processing apparatus according to claim 3, further comprising a suck element communicated with said selected recovery duct, for sucking said one of said plurality of processing solutions.

7. **(Previously Presented)** The substrate processing apparatus according to claim 3, wherein said rotating base and said atmosphere cutoff plate each have a disk-like shape and respective edge portions thereof facing said plurality of recovery ducts are vertical slide surfaces.

8. **(Previously Presented)** The substrate processing apparatus according to claim 3, wherein respective openings of said plurality of recovery ducts are vertically stacked at substantially the same position in a horizontal direction.

9. - 21. **(Canceled)**

22. **(Previously Presented)** The apparatus of claim 3, wherein the upper guide member of the selected duct and the lower guide member of another duct of said plurality of recovery ducts comprises the same member.